

What is claimed is:

1. A surface acoustic wave device comprising:  
a piezoelectric substrate;  
at least one IDT disposed on the piezoelectric substrate;  
an input end and an output end connected to the IDT, at  
least one of the input end and the output end including a pair  
of balanced signal terminals; and  
at least one of a delay line and a reactance component  
connected to one of the pair of balanced signal terminals.
2. A surface acoustic wave device according to claim 1,  
wherein the surface acoustic wave device is a longitudinally  
coupled resonator type surface acoustic wave filter in which  
at least three IDTs are disposed along the surface acoustic  
wave propagation direction.
3. A surface acoustic wave device according to claim 2,  
wherein the surface acoustic wave device includes a plurality  
of the longitudinally coupled resonator type surface acoustic  
wave filters.
4. A surface acoustic wave device according to claim 1,  
wherein there is no electrically neutral point between the  
first and second balanced signal terminals.
5. A surface acoustic wave device according to claim 1,  
further comprising a package and a microstrip line provided on  
one of the package and the piezoelectric substrate, wherein  
the microstrip line constitutes at least one of the delay line  
and the reactance component.
6. A surface acoustic wave device according to claim 5,  
further comprising a plurality of IDTs disposed on the

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piezoelectric substrate and housed inside the package such that the surface of the piezoelectric substrate having the IDTs disposed thereon facing downward.

7. A surface acoustic wave device according to claim 1, further comprising a package having electrodes disposed thereon, wherein the electrodes of the package are electrically connected to at least one of the input and output ends having the first and second balanced signal terminals via a bonding wire, and wherein the bonding wire constitutes at least one of the delay line and the reactance component.

8. A communication device containing a surface acoustic wave device according to claim 1.

9. A surface acoustic wave device comprising:  
a piezoelectric substrate,  
at least one IDT disposed on the piezoelectric substrate;  
an input end and an output end connected to the IDT, at least one of the input end and the output end including a pair of balanced signal terminals; and  
at least one of a plurality of delay lines and a plurality of reactance components connected to the pair of balanced signal terminals, respectively, and being different from each other.

10. A surface acoustic wave device according to claim 9, wherein the surface acoustic wave device is a longitudinally coupled resonator type surface acoustic wave filter in which at least three IDTs are disposed along the surface acoustic wave propagation direction.

11. A surface acoustic wave device according to claim 10,

wherein the surface acoustic wave device includes a plurality of the longitudinally coupled resonator type surface acoustic wave filters.

12. A surface acoustic wave device according to claim 9, wherein there is no electrically neutral point between the first and second balanced signal terminals.

13. A surface acoustic wave device according to claim 9, further comprising a package and a microstrip line provided on one of the package and the piezoelectric substrate, wherein the microstrip line constitutes at least one of the delay line and the reactance component.

14. A surface acoustic wave device according to claim 13, further comprising a plurality of IDTs disposed on the piezoelectric substrate and housed inside the package such that the surface of the piezoelectric substrate having the IDTs disposed thereon <sup>(S)</sup><sub>A</sub> facing downward.

15. A surface acoustic wave device according to claim 9, further comprising a package having electrodes disposed thereon, wherein the electrodes of the package are electrically connected to at least one of the input and output ends having the first and second balanced signal terminals via a bonding wire, and wherein the bonding wire constitutes at least one of the delay line and the reactance component.

16. A communication device containing a surface acoustic wave device according to claim 9.

17. A surface acoustic wave device comprising:  
a piezoelectric substrate;

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at least one IDT disposed on the piezoelectric substrate;  
an input end and an output end connected to the IDT, at  
least one of the input end and the output end including a pair  
of balanced signal terminals; and

a capacitance component connected between the pair of  
balanced signal terminals.

18. A surface acoustic wave device according to claim 17,  
wherein the surface acoustic wave device is a longitudinally  
coupled resonator type surface acoustic wave filter in which  
at least three IDTs are disposed along the surface acoustic  
wave propagation direction.

19. A surface acoustic wave device according to claim 18,  
wherein the surface acoustic wave device includes a plurality  
of the longitudinally coupled resonator type surface acoustic  
wave filters.

20. A surface acoustic wave device according to claim 17,  
wherein there is no electrically neutral point between the  
pair of balanced signal terminals.

21. A surface acoustic wave device according to claim 17,  
further comprising a package and a microstrip line provided on  
one of the package and the piezoelectric substrate, wherein  
the microstrip line constitutes the capacitance component.

22. A surface acoustic wave device according to claim 21,  
further comprising a plurality of IDTs disposed on the  
piezoelectric substrate and housed inside the package such  
that the surface of the piezoelectric substrate having the  
IDTs disposed thereon facing downward.

23. A surface acoustic wave device according to claim 17, further comprising a package having electrodes disposed thereon, wherein the electrodes of the package are electrically connected to at least one of the input and output ends having the pair of balanced signal terminals via a bonding wire, and wherein the bonding wire constitutes the capacitance component.

24. A communication device containing a surface acoustic wave device according to claim 17.

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